

Title (en)  
THERMALLY CONDUCTIVE POLYESTER MOLDING MATERIALS

Title (de)  
WÄRMELEITFÄHIGE POLYESTERFORMMASSEN

Title (fr)  
MATIÈRES MOULABLES À BASE DE POLYESTER THERMOCONDUCTRICES

Publication  
**EP 2081987 B1 20091223 (DE)**

Application  
**EP 07820796 A 20071002**

Priority  

- EP 2007060414 W 20071002
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Abstract (en)  
[origin: US2013270477A1] Thermoplastic molding compositions comprising A) from 10 to 69% by weight of a thermoplastic polyester B) from 30 to 79% by weight of an aluminum oxide C) from 0.01 to 10% by weight of an organic or inorganic acid or mixture of these D) from 0 to 10% by weight of D1) at least one highly branched or hyperbranched polycarbonate with an OH number of from 1 to 600 mg KOH/g of polycarbonate (to DIN 53240, part 2), or D2) at least one highly branched or hyperbranched polyester of AxBy type, where x is at least 1.1 and y is at least 2.1, or a mixture of these E) from 0 to 50% by weight of other additives, where the entirety of the percentages by weight of components A) to E) gives 100%.

IPC 8 full level  
**C08K 3/22** (2006.01)

CPC (source: EP KR US)  
**C08K 3/22** (2013.01 - KR); **C08K 5/09** (2013.01 - KR); **C08L 67/02** (2013.01 - EP KR US); **C08L 69/00** (2013.01 - KR); **C09K 5/14** (2013.01 - EP KR US); **C08K 3/22** (2013.01 - EP US); **C08K 5/09** (2013.01 - EP US); **C08K 2003/2227** (2013.01 - KR); **C08L 67/00** (2013.01 - EP US); **C08L 69/00** (2013.01 - EP US)

C-Set (source: EP US)  
**C08L 67/02** + **C08L 2666/18**

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